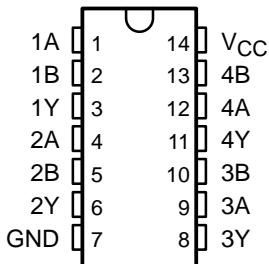
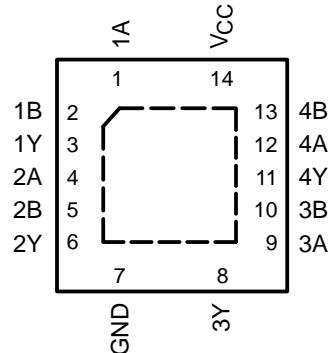


- Operating Range 2-V to 5.5-V  $V_{CC}$
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

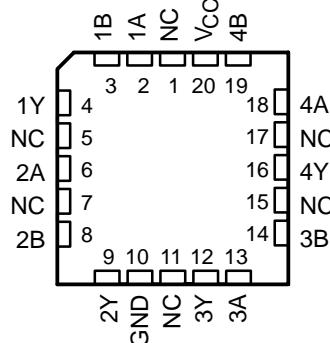
SN54AHC86 . . . J OR W PACKAGE  
SN74AHC86 . . . D, DB, DGV, N, NS,  
OR PW PACKAGE  
(TOP VIEW)



SN74AHC86 . . . RGY PACKAGE  
(TOP VIEW)



SN54AHC86 . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

### description/ordering information

The 'AHC86 devices are quadruple 2-input exclusive-OR gates. These devices perform the Boolean function  $Y = A \oplus B$  or  $Y = \bar{A}B + A\bar{B}$  in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

### ORDERING INFORMATION

T <sub>A</sub>	PACKAGE <sup>†</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QFN – RGY	Tape and reel	SN74AHC86RGYR
	PDIP – N	Tube	SN74AHC86N
	SOIC – D	Tube	SN74AHC86D
		Tape and reel	SN74AHC86DR
	SOP – NS	Tape and reel	SN74AHC86NSR
	SSOP – DB	Tape and reel	SN74AHC86DBR
	TSSOP – PW	Tube	SN74AHC86PW
		Tape and reel	SN74AHC86PWR
-55°C to 125°C	TVSOP – DGV	Tape and reel	SN74AHC86DGVR
	CDIP – J	Tube	SNJ54AHC86J
	CFP – W	Tube	SNJ54AHC86W
	LCCC – FK	Tube	SNJ54AHC86FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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# SN54AHC86, SN74AHC86 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES

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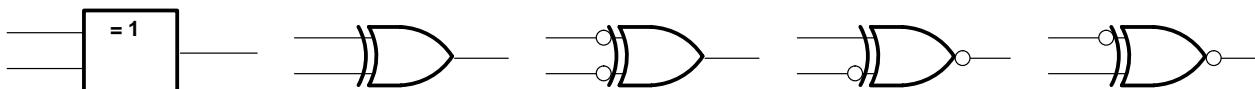
FUNCTION TABLE  
(each gate)

INPUTS		OUTPUT
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	L

## exclusive-OR logic

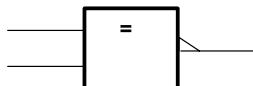
An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.

EXCLUSIVE OR



These are five equivalent exclusive-OR symbols valid for an SN74AHC86 gate in positive logic; negation may be shown at any two ports.

LOGIC-IDENTITY ELEMENT



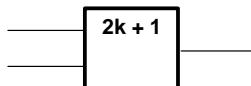
The output is active (low) if all inputs stand at the same logic level (i.e.,  $A = B$ ).

EVEN-PARITY ELEMENT



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

ODD-PARITY ELEMENT



The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	-0.5 V to 7 V
Output voltage range, $V_O$ (see Note 1) .....	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ ) .....	-20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) .....	$\pm 20$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	$\pm 25$ mA
Continuous current through $V_{CC}$ or GND .....	$\pm 50$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): D package .....	86°C/W
(see Note 2): DB package .....	96°C/W
(see Note 2): DGV package .....	127°C/W
(see Note 2): N package .....	80°C/W
(see Note 2): NS package .....	76°C/W
(see Note 2): PW package .....	113°C/W
(see Note 3): RGY package .....	47°C/W
Storage temperature range, $T_{STG}$ .....	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 2. The package thermal impedance is calculated in accordance with JEDEC 51-7.  
 3. The package thermal impedance is calculated in accordance with JEDEC 51-5.

**SN54AHC86, SN74AHC86**  
**QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES**

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**recommended operating conditions (see Note 4)**

		SN54AHC86		SN74AHC86		UNIT
		MIN	MAX	MIN	MAX	
V <sub>CC</sub>	Supply voltage	2	5.5	2	5.5	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V	1.5	1.5	1.5	V
		V <sub>CC</sub> = 3 V	2.1	2.1	2.1	
		V <sub>CC</sub> = 5.5 V	3.85	3.85	3.85	
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V	0.5	0.5	0.5	V
		V <sub>CC</sub> = 3 V	0.9	0.9	0.9	
		V <sub>CC</sub> = 5.5 V	1.65	1.65	1.65	
V <sub>I</sub>	Input voltage	0	5.5	0	5.5	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2 V	-50	-50	-50	μA
		V <sub>CC</sub> = 3.3 V ± 0.3 V	-4	-4	-4	mA
		V <sub>CC</sub> = 5 V ± 0.5 V	-8	-8	-8	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2 V	50	50	50	μA
		V <sub>CC</sub> = 3.3 V ± 0.3 V	4	4	4	mA
		V <sub>CC</sub> = 5 V ± 0.5 V	8	8	8	
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 3.3 V ± 0.3 V	100	100	100	ns/V
		V <sub>CC</sub> = 5 V ± 0.5 V	20	20	20	
T <sub>A</sub>	Operating free-air temperature	-55	125	-40	85	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54AHC86	SN74AHC86	UNIT
			MIN	TYP	MAX			
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	2 V	1.9	2	1.9	1.9	1.9	V
		3 V	2.9	3	2.9	2.9	2.9	
		4.5 V	4.4	4.5	4.4	4.4	4.4	
	I <sub>OH</sub> = -4 mA	3 V	2.58		2.48	2.48	2.48	
	I <sub>OH</sub> = -8 mA	4.5 V	3.94		3.8	3.8	3.8	
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	2 V		0.1	0.1	0.1	0.1	V
		3 V		0.1	0.1	0.1	0.1	
		4.5 V		0.1	0.1	0.1	0.1	
	I <sub>OL</sub> = 4 mA	3 V		0.36	0.5	0.5	0.44	
	I <sub>OL</sub> = 8 mA	4.5 V		0.36	0.5	0.5	0.44	
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V		±0.1	±1*	±1	±1	μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V		2	20	20	20	μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		4	10		10	pF

\* On products compliant to MIL-PRF-38535, this parameter is not production tested at V<sub>CC</sub> = 0 V.

# SN54AHC86, SN74AHC86 QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES

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**switching characteristics over recommended operating free-air temperature range,  
 $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$  (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54AHC86	SN74AHC86	UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{PLH}$	A or B	Y	$C_L = 15 \text{ pF}$	7*	11*	1*	13*	1	13
$t_{PHL}$				7*	11*	1*	13*	1	13
$t_{PLH}$	A or B	Y	$C_L = 50 \text{ pF}$	9.5	14.5	1	16.5	1	16.5
$t_{PHL}$				9.5	14.5	1	16.5	1	16.5

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

**switching characteristics over recommended operating free-air temperature range,  
 $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$  (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54AHC86	SN74AHC86	UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{PLH}$	A or B	Y	$C_L = 15 \text{ pF}$	4.8*	6.8*	1*	8*	1	8
$t_{PHL}$				4.8*	6.8*	1*	8*	1	8
$t_{PLH}$	A or B	Y	$C_L = 50 \text{ pF}$	6.3	8.8	1	10	1	10
$t_{PHL}$				6.3	8.8	1	10	1	10

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

**noise characteristics,  $V_{CC} = 5 \text{ V}$ ,  $C_L = 50 \text{ pF}$ ,  $T_A = 25^\circ\text{C}$  (see Note 5)**

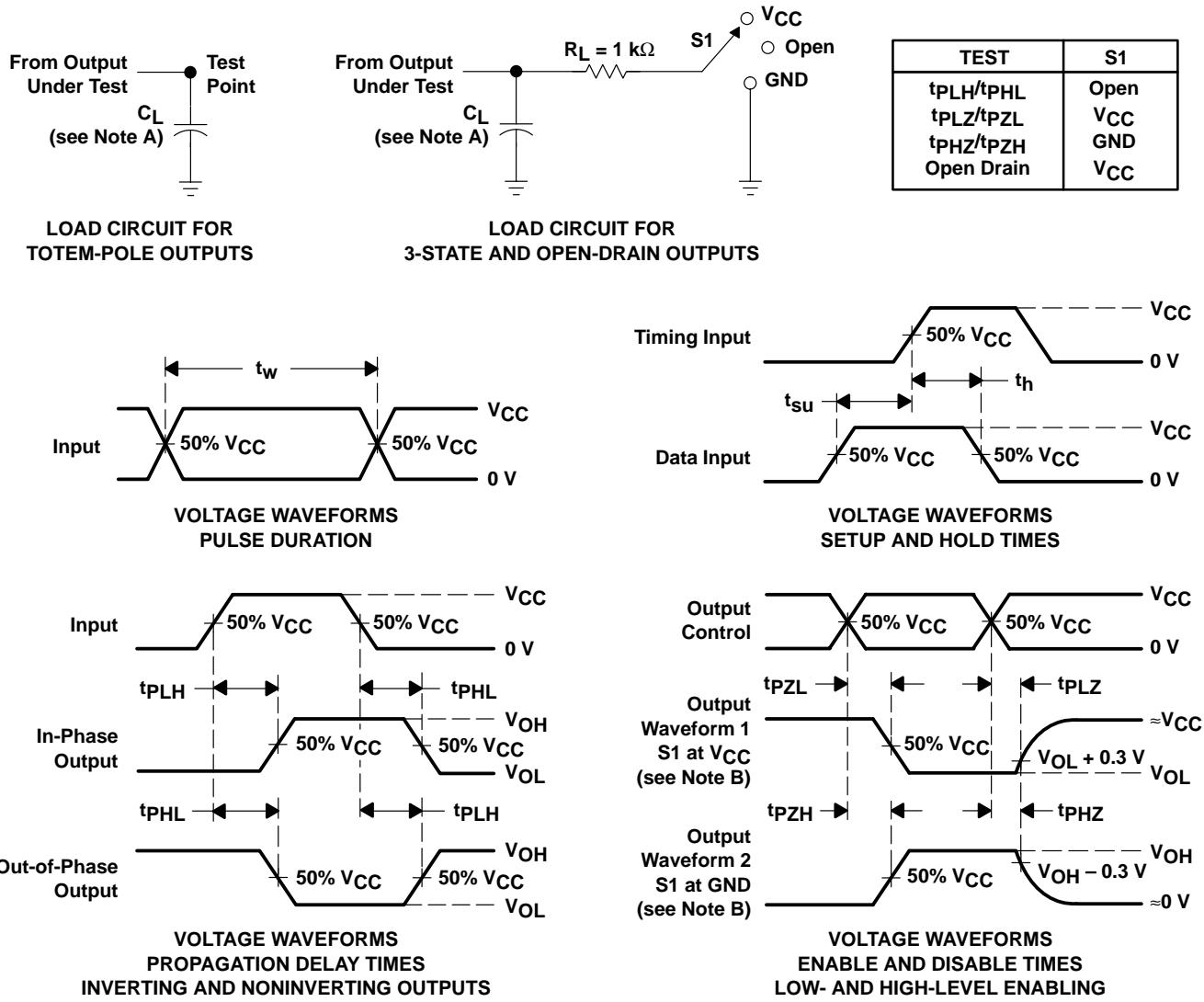
PARAMETER	SN74AHC86			UNIT
	MIN	TYP	MAX	
$V_{OL(P)}$ Quiet output, maximum dynamic $V_{OL}$	0.3	0.8	V	
$V_{OL(V)}$ Quiet output, minimum dynamic $V_{OL}$	-0.3	-0.8	V	
$V_{OH(V)}$ Quiet output, minimum dynamic $V_{OH}$	4.4		V	
$V_{IH(D)}$ High-level dynamic input voltage	3.5		V	
$V_{IL(D)}$ Low-level dynamic input voltage	1.5		V	

NOTE 5: Characteristics are for surface-mount packages only.

**operating characteristics,  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^\circ\text{C}$**

PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance	No load, $f = 1 \text{ MHz}$	18	pF

PARAMETER MEASUREMENT INFORMATION



NOTES:

- A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 3 \text{ ns}$ ,  $t_f \leq 3 \text{ ns}$ .
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9681601Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
5962-9681601QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9681601QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SN74AHC86D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC86DBLE	OBsolete	SSOP	DB	14		TBD	Call TI	Call TI
SN74AHC86DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC86DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC86DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC86DGVR	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC86DGVRE4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC86DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC86DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC86N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74AHC86NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC86NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC86PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC86PWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC86PWLE	OBsolete	TSSOP	PW	14		TBD	Call TI	Call TI
SN74AHC86PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC86PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC86RGYR	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SNJ54AHC86FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54AHC86J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54AHC86W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

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(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

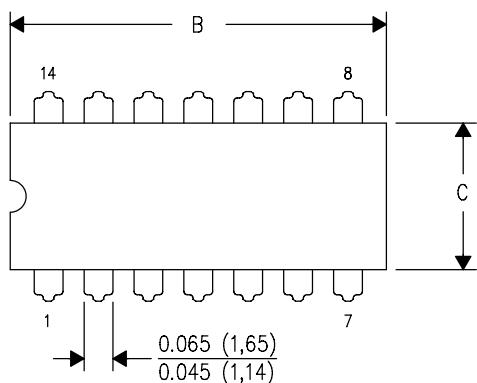
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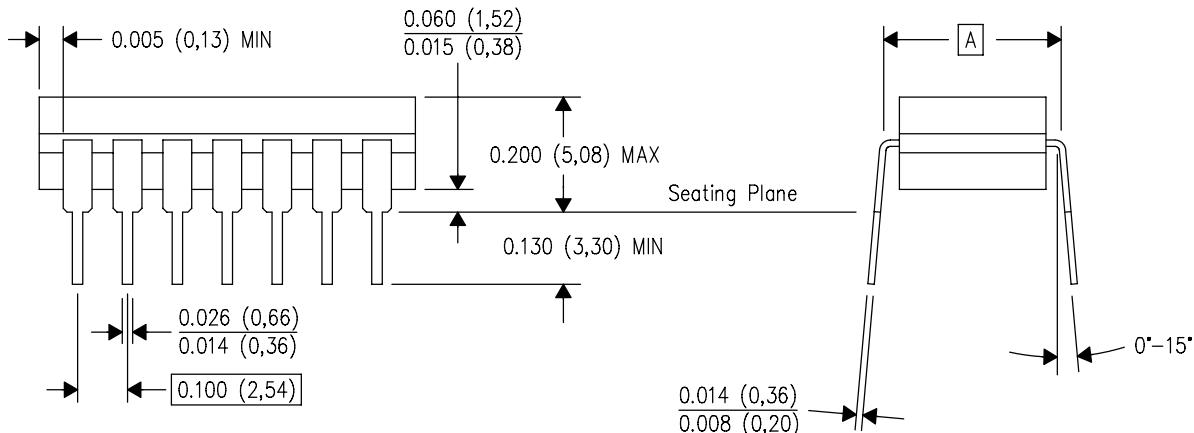
J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

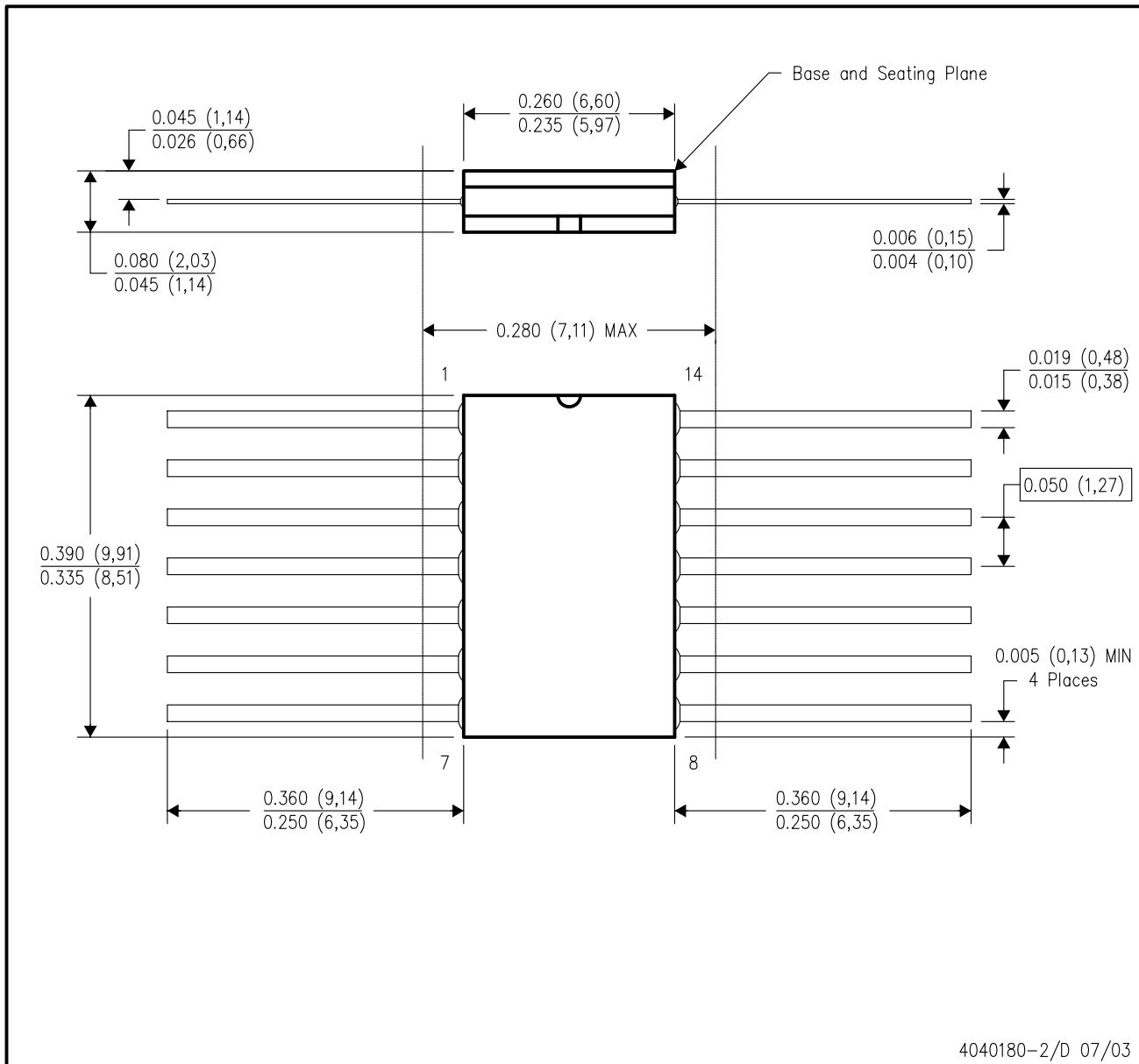


4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.  
C. This package is hermetically sealed with a ceramic lid using glass frit.  
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.  
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



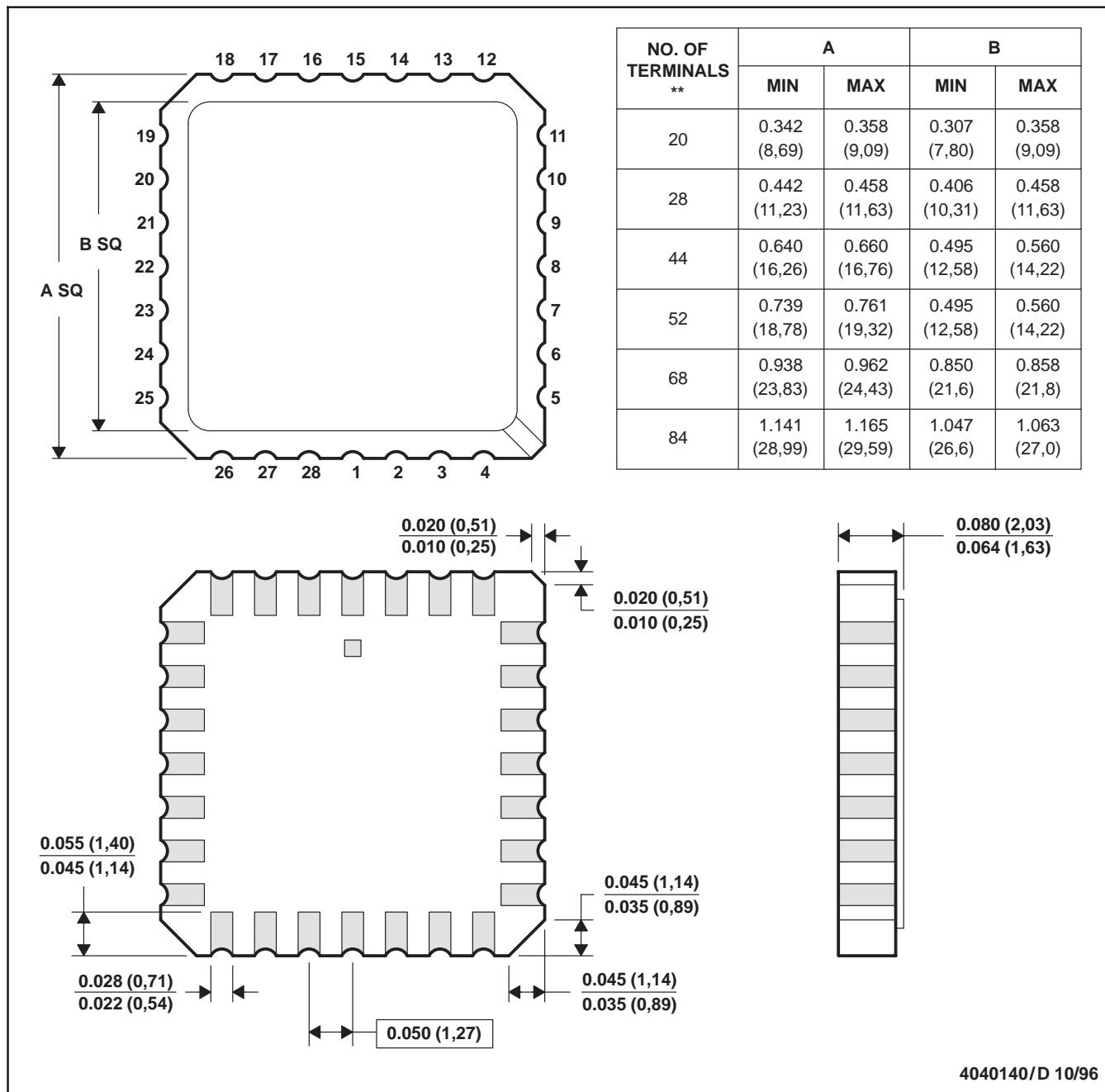
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within MIL-STD 1835 GDFP1-F14 and JEDEC MO-092AB

## FK (S-CQCC-N\*\*)

## LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a metal lid.

D. The terminals are gold plated.

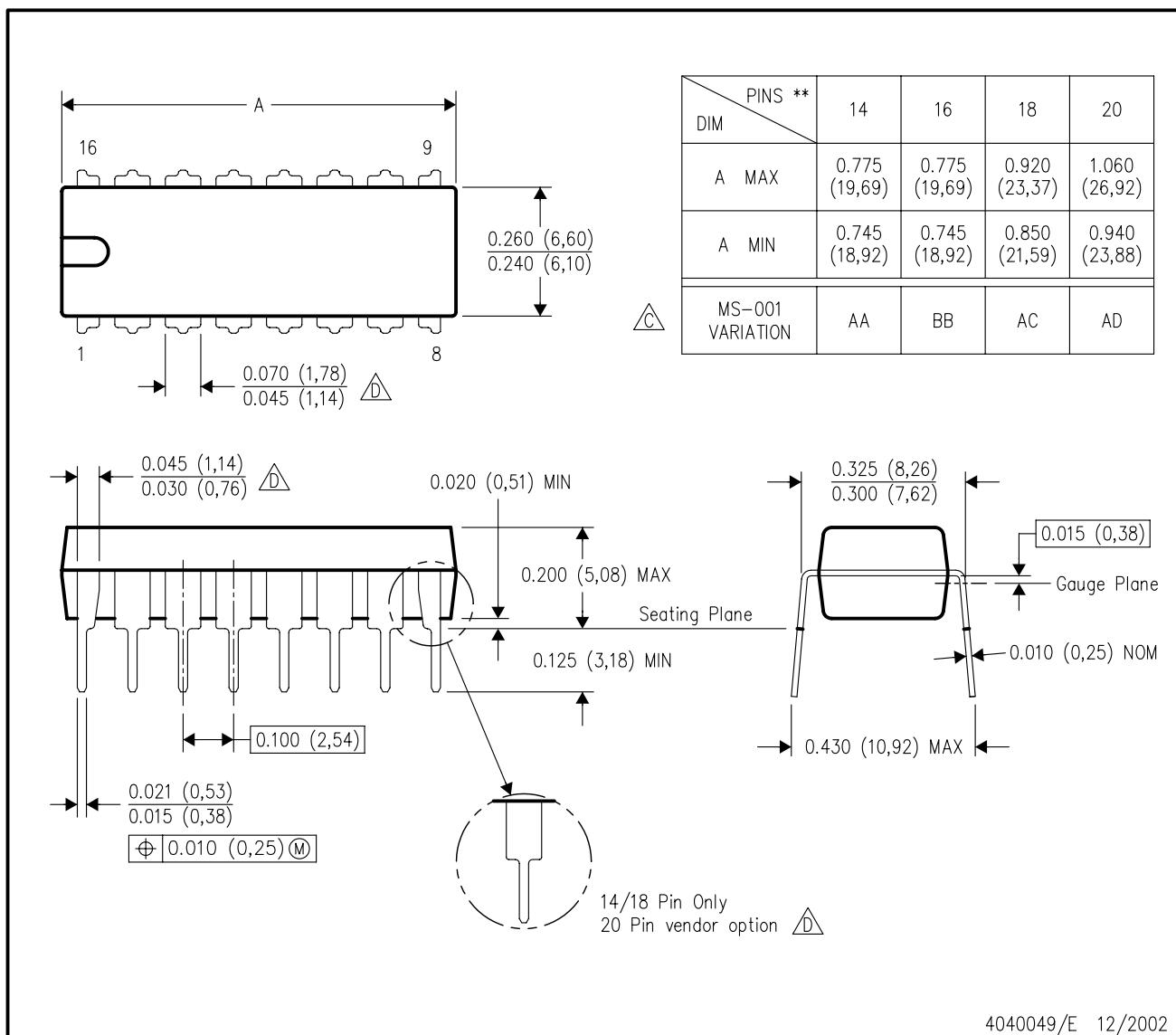
E. Falls within JEDEC MS-004

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## N (R-PDIP-T\*\*)

16 PINS SHOWN

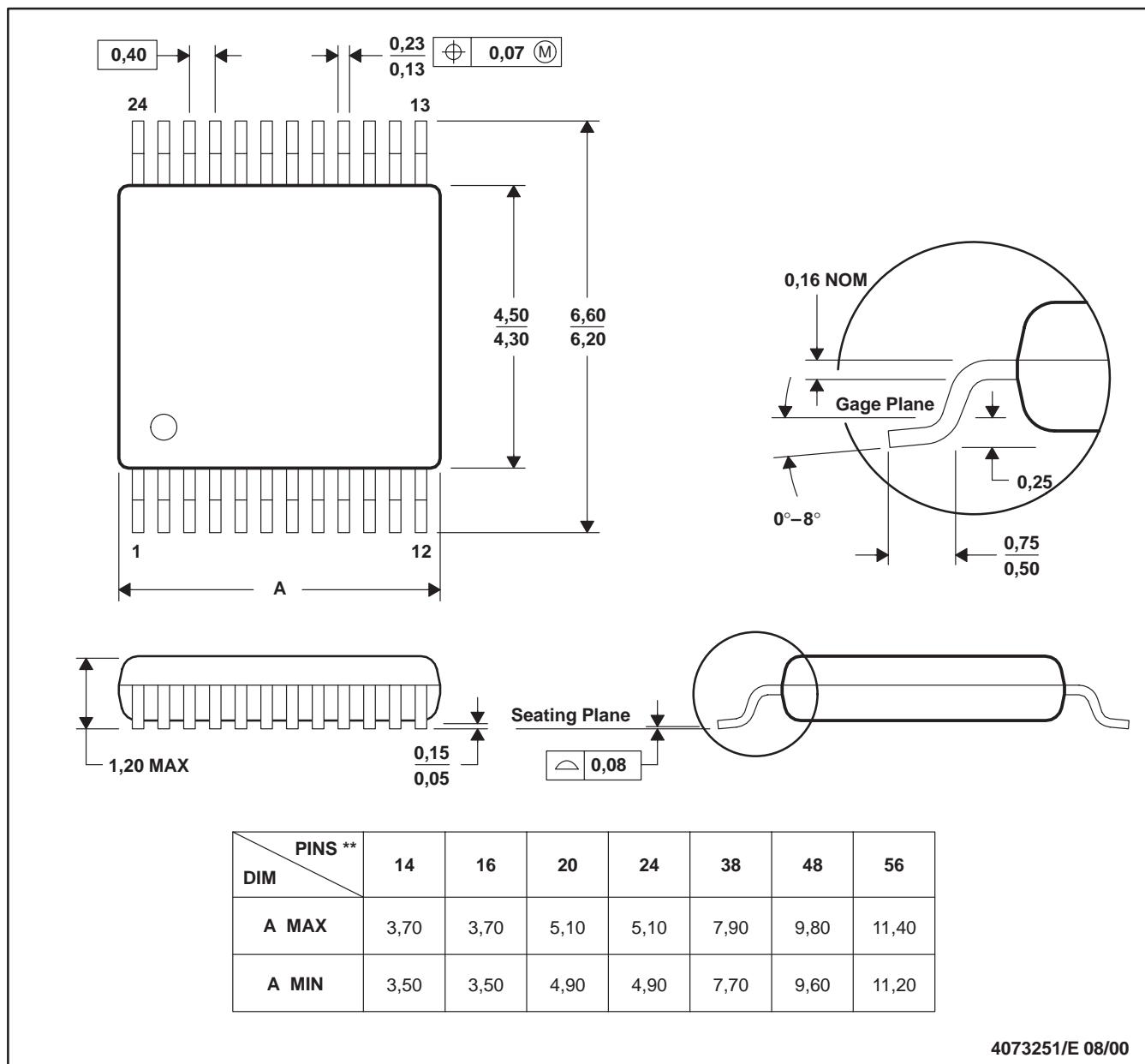
## PLASTIC DUAL-IN-LINE PACKAGE



## DGV (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

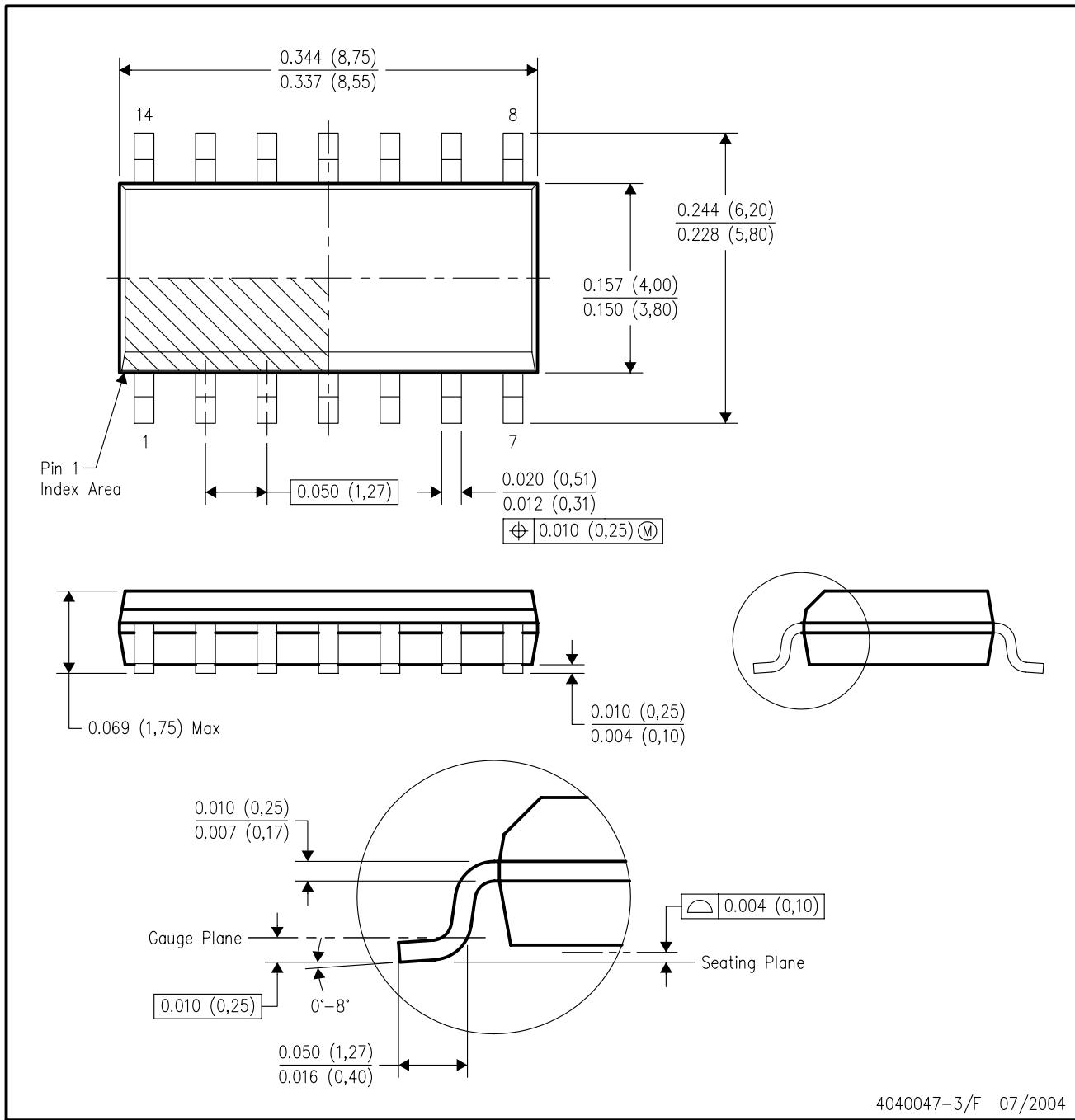
24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

## D (R-PDSO-G14)

## PLASTIC SMALL-OUTLINE PACKAGE

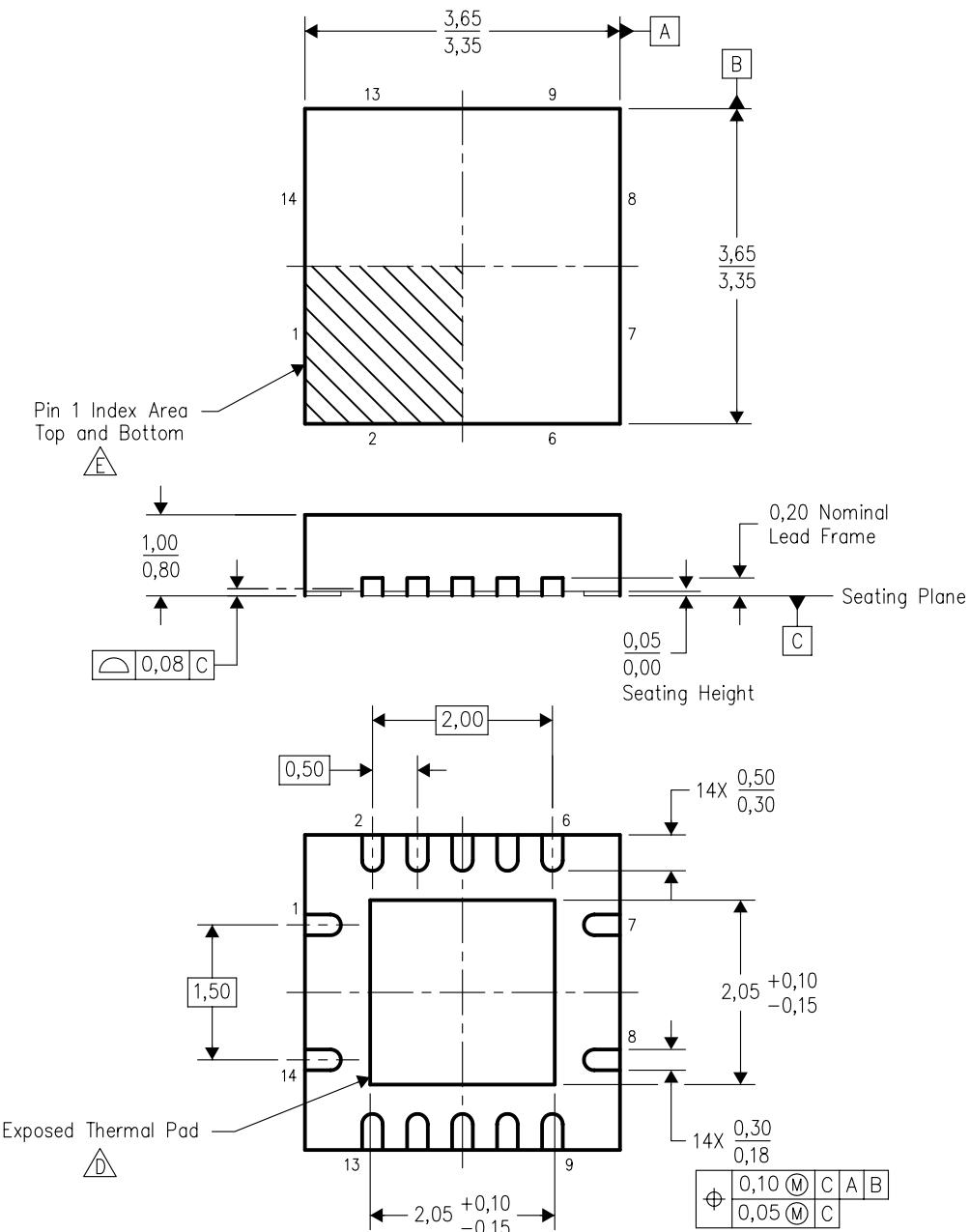


NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- Falls within JEDEC MS-012 variation AB.

RGY (S-PQFP-N14)

## PLASTIC QUAD FLATPACK



### Bottom View

4203539-2/G 04/2005

NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.  
B. This drawing is subject to change without notice.  
C. QFN (Quad Flatpack No-Lead) package configuration.

 The package thermal pad must be soldered to the board for thermal and mechanical performance.

 Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.

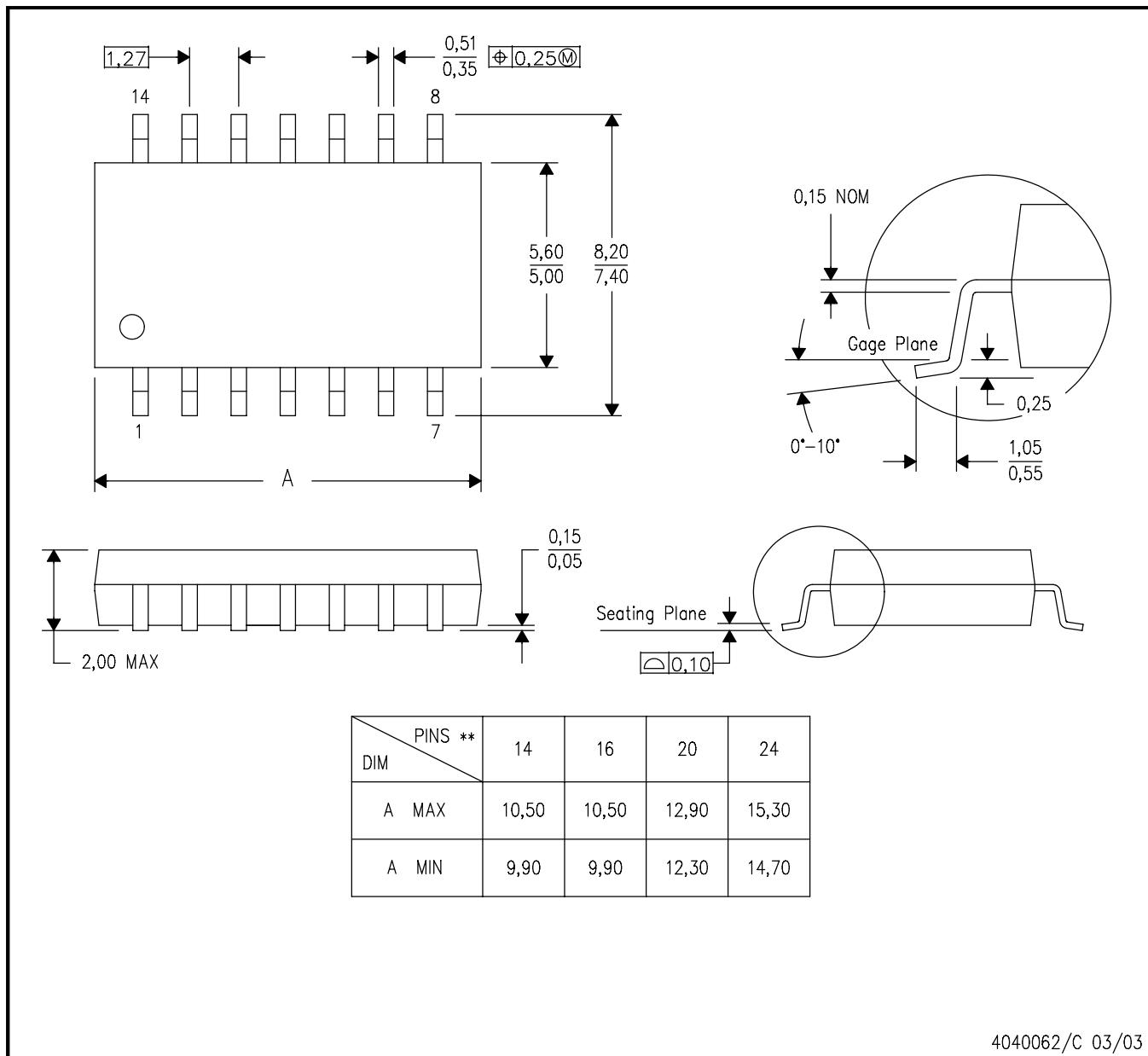
F. Package complies to JEDEC MO-241 variation BA.

## MECHANICAL DATA

## NS (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

**14-PINS SHOWN**

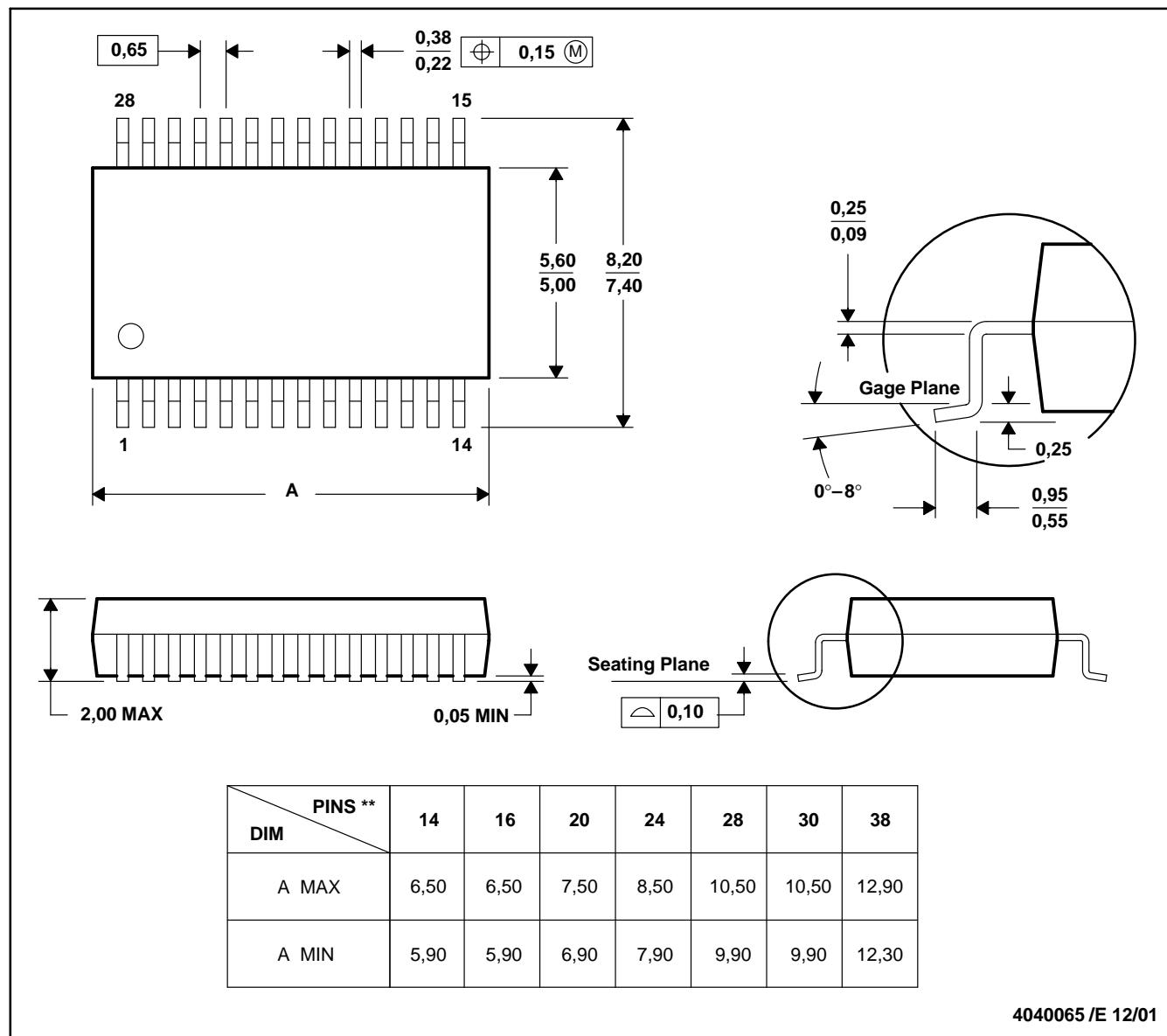


NOTES: A. All linear dimensions are in millimeters.  
B. This drawing is subject to change without notice.  
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

28 PINS SHOWN

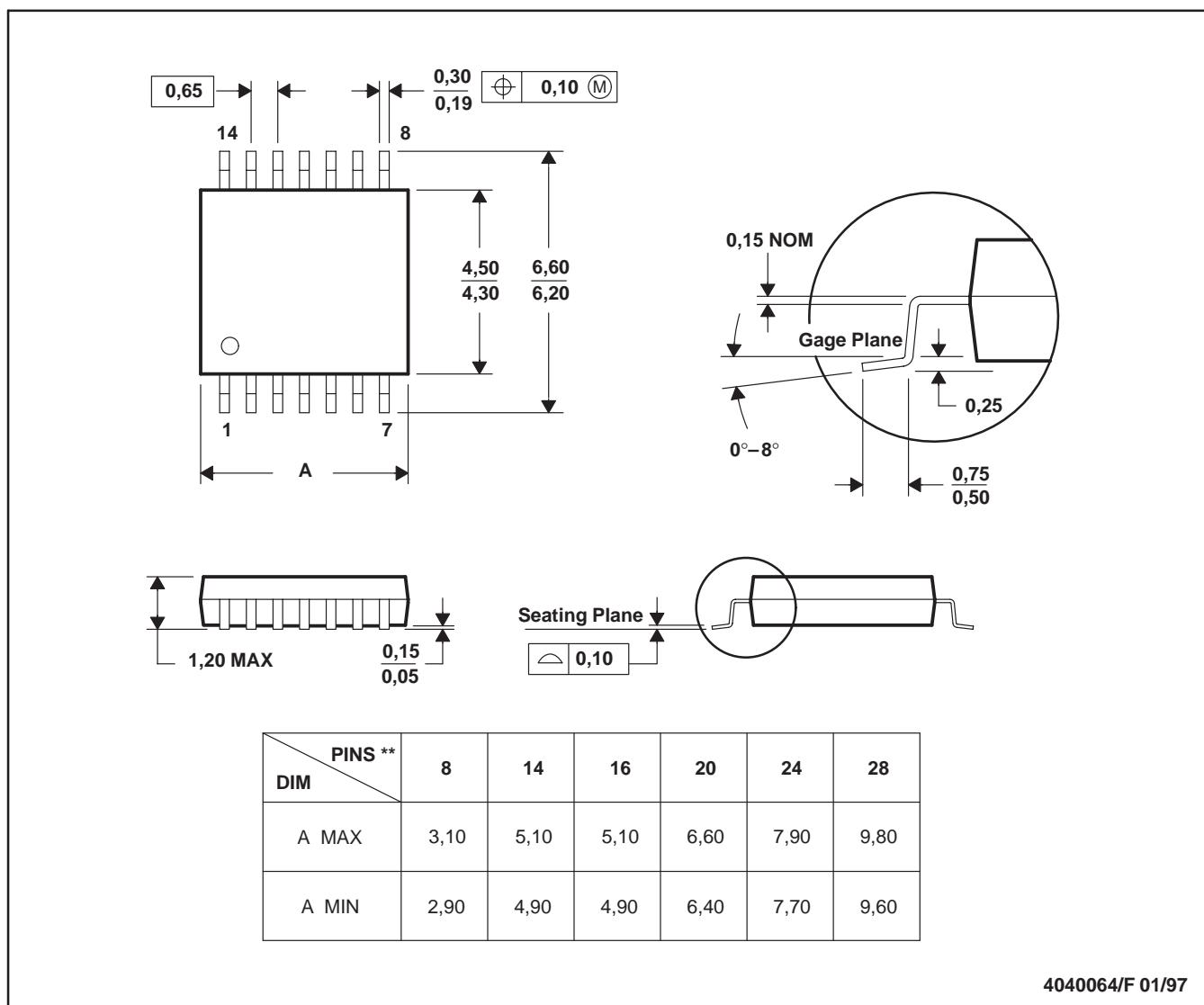


NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

## PW (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- Falls within JEDEC MO-153

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